



Product Change Notification - LIAL-22YHTT084 [\(Printer Friendly\)](#)

Date:

01 Feb 2018

Product Category:

Memory; 8-bit PIC Microcontrollers

Notification subject:

CCB 3227, 3227.001 Initial Notice: Qualification of CuPdAu bond wire in selected products of the 150K and 160K wafer technologies available in 8L SOIC package at GTK assembly site.

Notification text:**PCN Status:**

Initial notification

PCN Type:

Manufacturing Change

Microchip Parts Affected:

Please open the attachments found in the attachments field below labeled as PCN_#_Affected_CPN.

NOTE: For your convenience Microchip includes identical files in two formats (.pdf and .xls).

Description of Change:

Qualification of palladium coated copper with gold flash (CuPdAu) bond wire in selected products of the 150K and 160K wafer technologies available in 8L SOIC package at GTK assembly site.

Pre Change:

Using gold (Au) bond wire, CRM-1076DJ die attach and G600 mold compound material

Post Change:

Using palladium coated copper with gold flash (CuPdAu) bond wire, 4900GC die attach and G700 mold compound material.

Pre and Post Change Summary:

	Pre Change	Post Change
Assembly Site	Greatek Electronic Inc. (GTK)	Greatek Electronic Inc. (GTK)
Wire material	Au	CuPdAu
Die attach material	CRM-1076DJ	4900GC
Molding compound material	G600	G700
Lead frame material	A194	A194

Impacts to Data Sheet:

None

Change Impact:

None

Reason for Change:

To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) bond wire.

Change Implementation Status:

In Progress

Estimated Qualification Completion Date:

June 2018

Note: Please be advised the qualification completion times may be extended because of unforeseen business conditions however implementation will not occur until after qualification has completed and a final PCN has been issued. The final PCN will include the qualification report and estimated first ship date. Also note that after the estimated first ship date guided in the final PCN customers may receive pre and post change parts.

Time Table Summary:

	February 2018					-->	June 2018			
Workweek	05	06	07	08	09		23	24	25	26
Initial PCN Issue Date	X									
Qual Report Availability							X			

Final PCN Issue Date								X			
----------------------	--	--	--	--	--	--	--	---	--	--	--

Method to Identify Change:
Traceability code

Qualification Plan:
Please open the attachments included with this PCN labeled as PCN_#_Qual Plan.

Revision History:
February 01, 2018: Issued initial notification

The change described in this PCN does not alter Microchip’s current regulatory compliance regarding the material content of the applicable products.

- Attachment(s):**
- [PCN_LIAL-22YHTT084_ Qual_Plan.pdf](#)
 - [PCN_LIAL-22YHTT084_Affected CPN.pdf](#)
 - [PCN_LIAL-22YHTT084_Affected CPN.xls](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

Terms and Conditions:

If you wish to change your product/process change notification (PCN) profile please log on to our website at <http://www.microchip.com/PCN> sign into myMICROCHIP to open the myMICROCHIP home page, then select a profile option from the left navigation bar.

To opt out of future offer or information emails (other than product change notification emails), click here to go to [microchipDIRECT](#) and login, then click on the "My account" link, click on "Update profile" and un-check the box that states "Future offers or information about Microchip's products or services."

